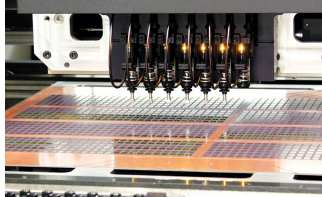


Build better with genuine Universal Instruments performance and reliability enhancements



Upgrade/Retrofit	Description	Prerequisites/Notes
FZ7™ Low-Force Placement Head	Achieve high-accuracy placement at forces from 30 to 5000 grams without spring-based or custom nozzles. Improve delicate part handling and reduce solder squeeze-out.	Requires Fuzion 4.x software or higher
Low-Force Nozzles	Leverage low-force functionality for applications requiring 40 to 150 grams of placement force. A lower-cost alternative to the Low-Force Placement Head.	Requires Fuzion 3.7 software or higher. 7-spindle placement heads only.
Look-Before-Pick Software Feature	Enable precision picking of devices with poor packaging constraints by leveraging nozzle tip alignment. Critical for small part handling or sensitive pick regions.	Requires Fuzion 4.x software or higher. May require 0.2 PEC for On-Axis lighting support.
4mm x 1mm ion™ Feeder	Feed components packaged in 4 x 1 tape with this dual-lane feeder. Supports both paper and embossed tape.	
Semiconductor Nozzles	Place a complete range of die with a portfolio of semi-conductor nozzles. Custom nozzles are available in a variety of materials.	

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